

**Amendments to the Claims**

**Claims 1-4 (*Cancelled*)**

5. (*Original*) An electronic device provided with an electric element and an encapsulation of electrically insulating material, and a carrier with a first side facing the element and an opposed second side, said carrier comprising:

- a patterned connection layer
- contact pads for coupling to an external carrier or an

element, and

- an intermediate layer of electrically conductive material, which is patterned so as to create interconnects between the interconnection layer and the contact pads, interconnects are mutually isolated by isolation areas, the encapsulation extending into the isolation areas,

- wherein a protective layer is present at the second side of the carrier so as to protect an interface between the intermediate layer and the contact pads.

6. (*Original*) An electronic device as claimed in Claim 5, wherein the bond pads and any other conducting elements at the first side of the carrier are mechanically anchored in the encapsulation.

7. (*Previously Presented*) An electronic device as claimed in claim 5, wherein at least a number of contact pads is laterally displaced with respect to the corresponding bond pads.

8. (*Original*) An electronic device as claimed in Claim 5, wherein the protective layer laterally extends so as to cover the intermediate layer.

9. (*Original*) An electronic device as claimed in Claim 5, wherein:

- the contact pads comprise a main layer and a masking layer, said masking layer being present at the second side of the carrier and having a larger surface area than the main layer, and

- the protective layer is substantially present between the masking layer and the intermediate layer, such that on perpendicular projection of the protective layer on the masking layer there is a substantial overlap.

10. (*Original*) An electronic device as claimed in Claim 5, wherein the electric element is a semiconductor device, that is at least partially encapsulated in the encapsulation.